LL24BT1006D

List

LL24BT1006D

30W Ultra Low Capacitance Bi-Directional TVS For ESD Protection 24V

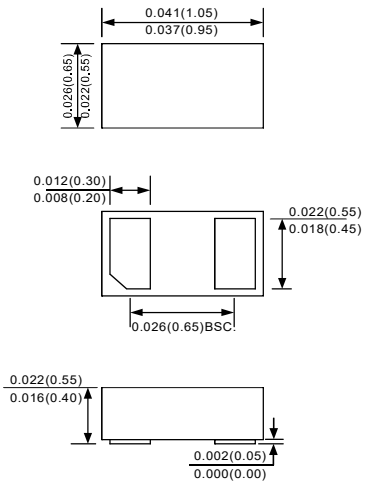
Features

- Array of surge rated diodes with internal TVS diode.
- Protects I/O lines.
- Each I/O pin can withstand over 1000 ESD strikes for ±8kV contact discharge.
- Transient protection for high-speed data lines:
  IEC 61000-4-2 (ESD) ±10kV(Air), ±10kV(Contact).
  IEC 61000-4-5 (Lightning) 6A (8/20μs).
  Cable discharge event (CDE).
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex.LL24BT1006D-H.

Mechanical data

- Epoxy: UL94V-0 rated flame retardant.
- Case : Molded plastic, T1006P2.

Package outline



Dimensions in inches and (millimeters)

Maximum ratings (At T_A=25°C unless otherwise noted)

Parameter	Symbol	Ratings	Units
Peak pulse current (8/20μs)	I_{PP}	6	A
Peak pulse power (8/20μs)	P_{PK}	30	W
ESD per IEC 61000-4-2 (Contact)	V_{ESD}	±10	KV
ESD per IEC 61000-4-2 (Air)		±10	
Charged device model	CDM	±1000	V
Machine model	MM	±200	V
Operating temperature	T_J	+125	°C
Storage temperature range	T_{STG}	-55 to +150	°C

Electrical characteristics (At T_A=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Reverse stand-off voltage		V_{RWM}			24	V
Reverse leakage current	V_{RWM}=24V, T=25°C	I_R			1	μA
Breakdown voltage	I_T=100μA	V_{BR}	25	26		V
Clamping voltage	I_{PP}=6A, t_p=8/20μs	V_C		5.5		V
Clamping voltage	I_{PP}=8A, t_p=100ns (note1)	V_C		5		V
	I_{PP}=16A, t_p=100ns (note1)			7.3		
Dynamic resistance	I_{PP}=12A, t_p=100ns (note1)	R_{dyn}		0.29		Ω
Parasitic capacitance	V_R=0V, f=1.0MHz	C_{ESD}		0.2		pF

Note: 1. Measurements performed using a 100ns transmission line pulse (TLP) system.

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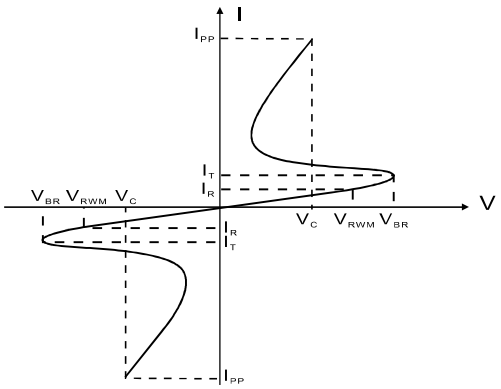
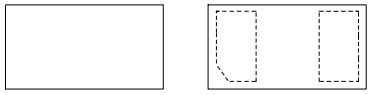
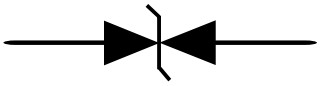
Rating and characteristic curves

Symbol	Parameter
V_{RWM}	Nominal reverse working voltage
I_R	Reverse leakage current@ V_{RWM}
V_{BR}	Reverse breakdown voltage@ I_T
I_T	Test current for reverse breakdown
V_C	Clamping voltage @ I_{PP}
I_{PP}	Maximym peak pulse current
C_{ESD}	Parasitic capacitance



Pinning information

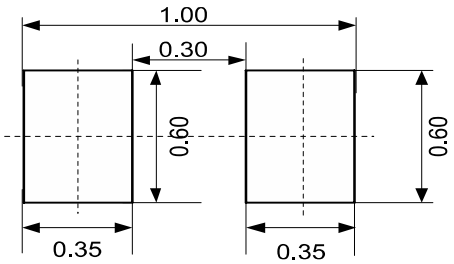
Pin	Simplified outline	Symbol
Bi-directional	 Top view Bottom view	

Marking

Type number	Marking code
LL24BT1006D	MX

*"M" is part number.
"X" is the internal code.

Suggested solder pad layout



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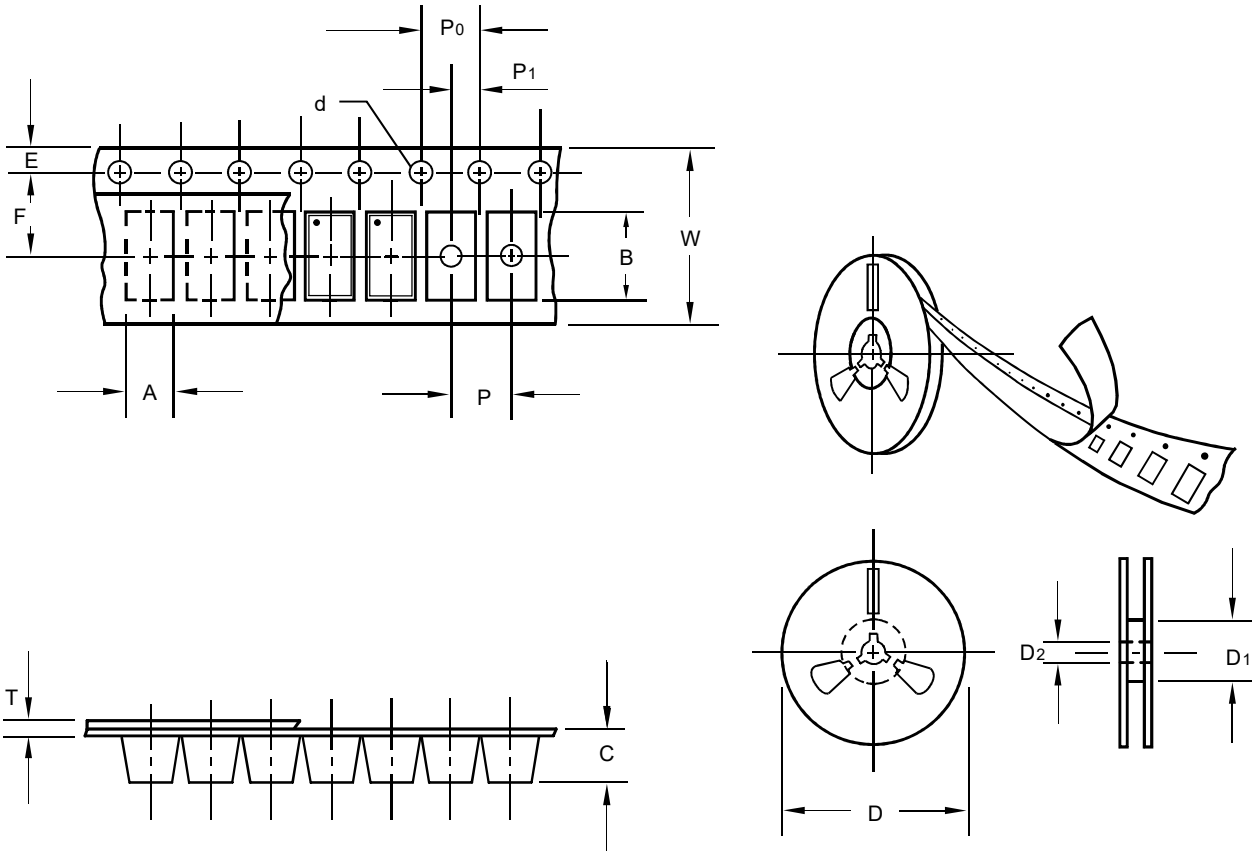
Packing information



unit:mm

Item	Symbol	Tolerance	T1006P2
Carrier width	A	0.1	0.27
Carrier length	B	0.1	0.50
Carrier depth	C	0.1	0.17
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D_1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D_1	min	55.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.20
Tape width	W	0.3	8.00

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

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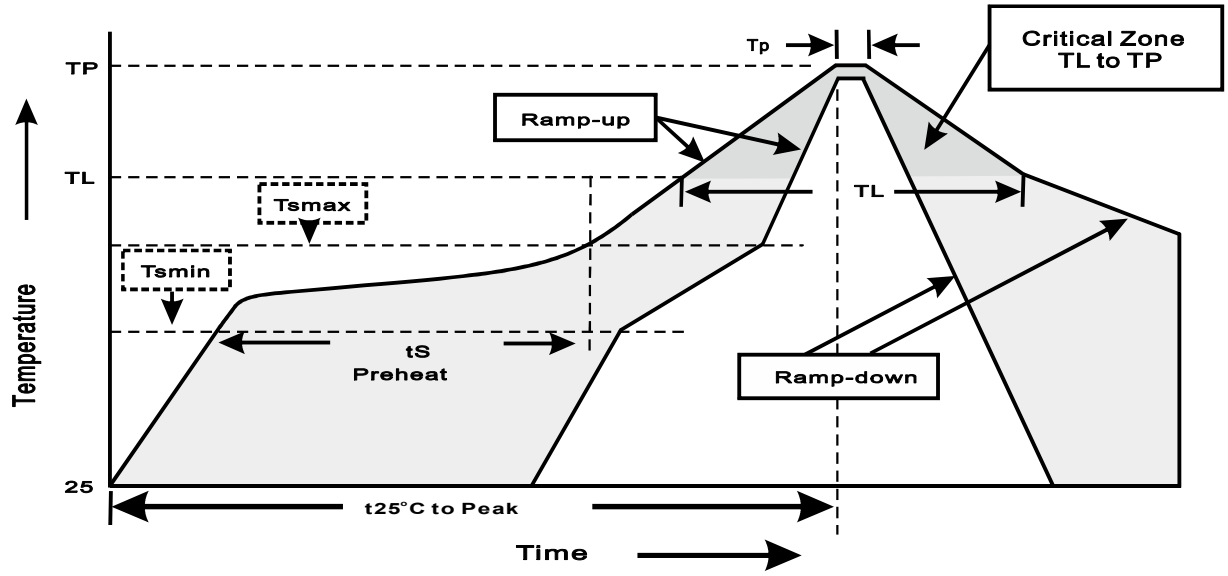
Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
T1006P2	7"	10,000	4.0	100,000	183*123*183	178	382*257*387	800,000

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	 150°C 200°C 60~120sec
Tsmax to T_L -Ramp-upRate	 <3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	 217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes